

60125 U.S. PTO  
08/916629

**LIST OF PRIOR ART  
CITED BY APPLICANTS**

Docket No.: 96-0098

Filing Date: 8/22/96

Applicants: CHAD A. COBBLEY  
TONGBI JIANG  
ED A. SCHROCK

# 2

Serial No.:

08/916,629

Sheet 1 of 3

**U.S. PATENT DOCUMENTS**

Exam. Initial		DOCUMENT #	DATE	NAME	CLASS	SUB CLASS
<i>L.M.</i>	<b>A</b>	5,288,794	2/22/94	Attarwala	524	714
	<b>B</b>	5,328,944	7/12/94	Attarwala et al.	524	83
	<b>C</b>	5,386,047	1/31/95	Nakos et al.	556	416
	<b>D</b>	5,424,343	6/13/95	Attarwala	524	83
	<b>E</b>	Re 32,889	3/14/89	Litke	523	212
	<b>F</b>	4,295,909	10/20/81	Baccei	156	307
	<b>G</b>	5,079,098	1/7/92	Liu	428	522
	<b>H</b>	5,589,554	12/31/96	Hiraoka	525	530
	<b>I</b>	5,536,799	7/16/96	Takahashi et al.	526	298
<i>L.M.</i>	<b>J</b>	4,309,526	1/5/82	Baccei	528	75

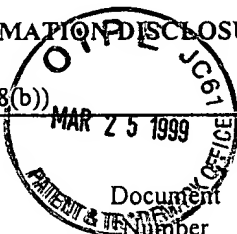
**FOREIGN PATENT DOCUMENTS**

DOCUMENT #	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES NO

<b>LIST OF PRIOR ART CITED BY APPLICANTS</b>		Docket No.: 96-0098	Filing Date: 8/22/97
		Applicants: CHAD A. COBBLEY TONGBI JIANG ED A. SCHROCK	
		Serial No.: 08/916,629	Sheet 2 of 3
<b>OTHER REFERENCES</b> (including Author, Title, Date, Pertinent Pages, etc.)			
121.	<b>K</b>	Chorbadjiev, K.G. and Kotzev, D. L., "The effect of fillers upon the properties of electroconductive cyanoacrylate adhesives", Int. J. Adhesion and Adhesives, Vol 8, No. 3, July 1988, pgs 143-146.	
	<b>L</b>	Melody, David P., "Advances in Room Temperature Curing Adhesives and Sealants-A Review", British Polymer Journal, Vol. 21, No. 2, 1989, Printed in Great Britain, pgs 175-179.	
	<b>M</b>	LOCTITE, product description sheet, Rocky Hill, CT., December 1996.	
	<b>N</b>	Loctite Corporation, "VARIDOT™ Surface Mount Adhesive Printing Process", advertising brochure, Rocky Hill, CT.	
	<b>O</b>	Millet, George H., "Properties of Cyanoacrylates - an Overview", Adhesives Age, October 1981, pgs 27-32.	
	<b>P</b>	Microelectronics Packaging Handbook, 1989, pgs 554-557.	
	<b>Q</b>	Pepper, D. C., "Kinetics and Mechanisms of Zwitterionic Polymerizations, Polymer Journal, Vol 12, No. 9, pgs 629-637 (1980).	
	<b>R</b>	VanZant, Peter, <i>Microchip Fabrication</i> , Second Edition, 1990, pgs 485-487.	
	<b>S</b>	Vijayalakshmi, V. et al., "Synthesis of 3-Substituted-2-cyanoacrylates: Their Evaluation as Cross-linkers in Cyanoacrylate Adhesive Compositions", Journal of Applied Polymer Science, Vol 49. 1993, pgs 1387-1394.	
✓ 121.	<b>T</b>	Palmer, Bentley J. et al., "A New Photoinitiator for Anionic Polymerization, <i>Macromolecules</i> , 1995, pgs 1328-1329.	

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		Serial No.: 08/916,629	Sheet 3 of 3
SM.	U	Negulescu, Ioan I. et al., "Thermal Behavior of Poly( $\alpha$ Cyanoacrylates)S, J. Macromol. Sci-Chem, A24(1),1987, pgs 75-83.	
	V	O'Connor, John T. and Attarwala, Shabbir, "Recent Breakthroughs in Thermal Resistant Cyanoacrylate Instant Adhesives", technical paper, Society of Manufacturing Engineers, 1993.	
	W	Drain, K. F., et al., "The effect of moisture on the strength of polycarbonate-cyanoacrylate adhesive bonds, Int. J.Adhesion and Adhesives, July 1985, pgs. 133-136.	
	X	Rooney, John M., "Thermal Degradation of Methyl and Ethyl Cyanoacrylate Oligomers, The British Polymer Journal, December 1981, pgs 160-163.	
	Y	Lee, Ju-Yeon, "Synthesis and Ring-Opening Polymerization of 3-Methoxy-4-cyano-2, 9-dioxabicyclo[4.3.0]non-3-ene: Preparation of Alternating Head-to-Head Copolymer of Methyl $\alpha$ -cyanoacrylate and 2,3-Dihydrofuran, Journal of Polymer Science: Vol. 27, 1989, pgs. 85-91.	
	Z	Cooke, B. D. and Allen, K. W., "Cyanoacrylates and their acid values", Int. J. Adhesion and Adhesives, Vol. 13 No. 2, April 1993, pgs 73-76.	
	AA	Ito, Hiroshi, "Thermal Deesterification and Decarboxylation of Alternating Copolymers of Styrene with $\beta$ -Substituted <i>t</i> -Butyl $\alpha$ -Cyanoacrylates, Journal of Polymer Science, Vol 27, 1989, pgs 2871-2881.	
	AB	Stein, Michael, "Thermal Behavior of Various Poly (2-Cyanoacrylate)S, Journal of Applied Poly Science: (1991), pgs 441-447.	
SM.	AC	Mikuni, Hiroyuki et al., "Morphological Study of Cyanoacrylate Adhesive Modified by Poly(butadiene-co-acrylonitrile)", Polym. Networks Blends, 5(3), 1995, pgs 159-162.	
Examiner: <i>LL A. Met</i>		Date Considered: 4/30/99	

FORM: PTO-1449 (REV: 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	Atty Docket No: <b>97-0098</b>	Serial No: <b>08/916,629</b>
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b)) (use several sheets if necessary)		Applicant: <b>Cobbley et al.</b>	
		Filing Date: <b>8/22/97</b>	Group: <b>2814 1733</b>



## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	
<i>S.M.</i>	AA	5,861,678	1/19/99	Schrock	257	783
	AB					
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					
	AK					

## FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes	No
	AL					<input type="checkbox"/>	<input type="checkbox"/>
	AM					<input type="checkbox"/>	<input type="checkbox"/>
	AN					<input type="checkbox"/>	<input type="checkbox"/>
	AO					<input type="checkbox"/>	<input type="checkbox"/>
	AP					<input type="checkbox"/>	<input type="checkbox"/>
	AQ					<input type="checkbox"/>	<input type="checkbox"/>

Initial

OTHER ART (including author, title, date, pertinent pages, etc.)

<i>S.M.</i>	AR		Denchev, Z. Z. & Kabaivanov, V. S., "Thermal Behaviour and Adhesive Properties of Some Cyanoacrylate Adhesives with Increased Heat Resistance", J. Appl. Polym. Sci., Vol 47, 1993, pgs 1019-1026.
<i>S.M.</i>	AS		Okamoto, Y. & Klemarczyk P. T., "Bonding Non-Polar Plastics with Alky Cyanoacrylate Instant Adhesive", ANTEC '91, pgs. 1114-1117.
	AT		

RECEIVED

MAR 31 1999

Examiner: <i>Sl. A. M.</i>	Date Considered: <i>4/30/99</i>	TECHNOLOGY CENTER 2800
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.